

# PATENT ABSTRACTS OF JAPAN

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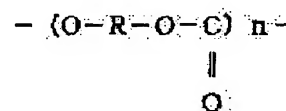
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## (54) THERMALLY CONDUCTIVE PRESSURE-SENSITIVE ADHESIVE AND ADHESIVE SHEET AND THE LIKE PREPARED THEREFROM

### (57)Abstract:

PROBLEM TO BE SOLVED: To obtain a thermally conductive pressure-sensitive adhesive excellent in adhesiveness and thermal conductivity without being limited by the kind or content of a thermally conductive filler by compounding a polymer having a polycarbonate structure contg. specific repeating units with a thermally conductive filler.

SOLUTION: This adhesive is prepd. by compounding 100 pts.wt. polyester polymer with 10-30 pts.wt. thermally conductive filler. The polyester polymer has a wt. average mol. wt. of 10,000 or higher and is prepd. from a diol component essentially contg. a polymer (pref. a polycarbonate diol) having a polycarbonate structure contg. repeating units represented by the formula (R is a 2-20C linear or branched hydrocarbon group) and a dicarboxylic acid component essentially contg. a dicarboxylic acid having a 2-20C aliph. or alicyclic hydrocarbon group as the molecular backbone. A thermally conductive pressure-sensitive adhesive sheet and the like are obt'd. by forming a layer of the adhesive on at least one side of a substrate and converting the coated susbtitute into the form of a sheet, a tape, etc.



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